Fraunhofer IZM

FRAUNHOFER INSTITUTE FOR RELIABILITY AND MICROINTEGRATION IZM

PRESS RELEASE

Next generation of FO-PLP and IC-Substrates

EVATEC AG and Fraunhofer IZM are cooperating in the field of advanced organic IC substrates and fan-out Panel Level Packaging. Focus is on advanced thin film etching technology for panel sizes up to 650x650 mm. New equipment as part of the Research Fab Microelectronics Germany (FMD) has been recently installed in Berlin.

EVATEC AG, a leading supplier of thin film equipment and process solutions in Advanced Packaging, Semiconductor, Optoelectronics and Photonics applications, has successfully completed the installation of a Clusterline 600 Panel Level Packaging Etch system at Fraunhofer IZM, Berlin.

The CLN600 platform is a dedicated Etch and Sputter equipment for FO-PLP and next generation IC-Substrates that supports panel sizes up to 650x650 mm and is the leading solution in this markets. The installed Etch System delivers superior etch uniformity across large scale substrates and is capable to perform physical Ar Etch as well as RIE (Reactive Ion Etching) and DRIE (Deep Reactive Ion Etching) applications.

With this installation, EVATEC AG has enhanced its leadership position in the growing panel level packaging segment. The tool is prepared to support process and technology development programs such as the Panel Level Packaging Consortium 2.0. In order to address these challenges, further equipment installations were made at Fraunhofer IZM in the run-up to PLC 2.0. We would also like to thank the Federal Ministry of Education and Research of Germany (BMBF) for funding the project Research Fab Microelectronics Germany (funding code 16FMD01K, 16FMD02 and 16FMD03).

Fraunhofer IZM is proud to have this state of the art CLN600 System platform in their equipment park and to mount on EVATEC AG as a strategic partner. "We are excited about the new opportunities and capabilities this system offers to the institute in the very dynamic Panel Level Packaging environment." says Lars Böttcher, a scientist at Fraunhofer IZM and expert in PLP.

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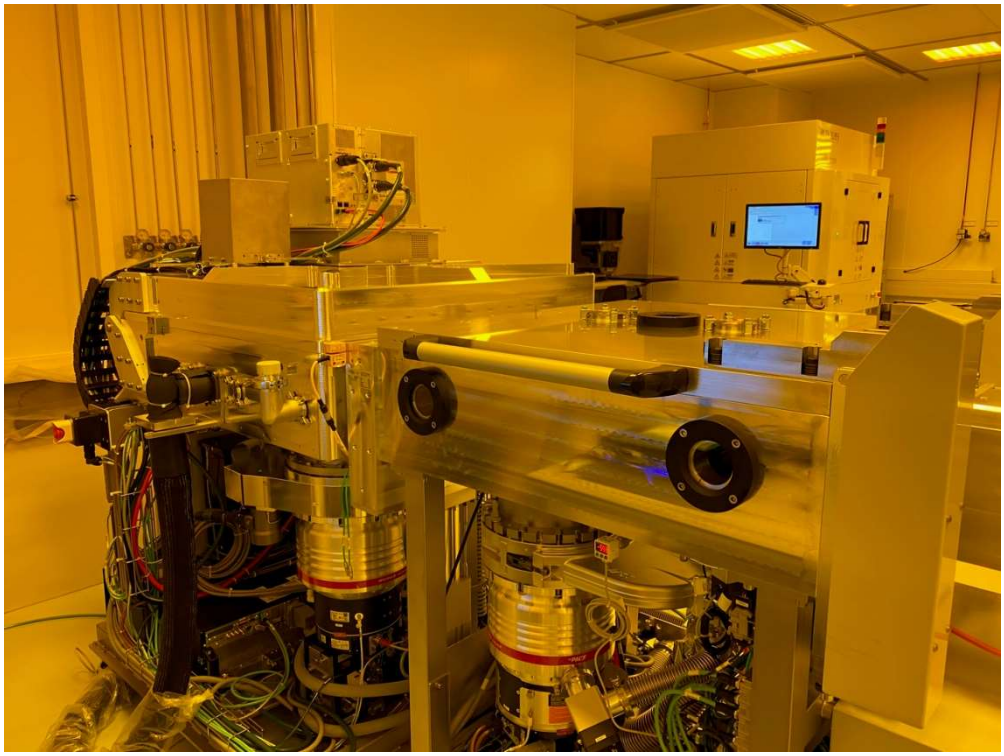

The CLN600 platform is a dedicated Etch and Sputter equipment for FO-PLP and next generation IC-Substrates is located at the Fraunhofer IZM in Berlin. © Fraunhofer IZM / Evatec

Fraunhofer IZM: Invisible -but indispensable: nothing works without highly integrated microelectronics and microsystems technology. The basis for their integration into products is the availability of reliable and cost-effective packaging and interconnection technologies. Fraunhofer IZM, a world leader in the development and reliability assessment of electronic packaging technologies, provides itscustomers with customized system integration technologies at wafer, chip and board level. Research at Fraunhofer IZM also means making electronics more reliable and providing its customers with reliable information on the durability of the electronics.

The Institute is one of the thirteen members of the Research Fab Microelectronics Germany FMD – the prime provider of applied research, development, and innovations in micro and nano-electronics, supported by the Germany Federal Ministry of Education and Research. The FMD offers its diverse clients a single source for access to R&D services, applied solutions, and novel, but highly mature technologies. www.forschungsfabrik-mikroelektronik.de

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